

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A component mounting system, configured by connecting a plurality of devices, for manufacturing a mounted board by placing and soldering a component onto the board, said component mounting system comprising:

(a) a printer for printing solder onto an electrode formed on said board;

(b) a first inspection unit for detecting a position of said printed solder and outputting a solder position detection result;

a 2 | (c) a component mounting unit for picking up said component ~~from a component feeder carriage with a mounting head~~, and placing said component on said board;

(d) a second inspection unit for detecting a position of said component placed and outputting a component position detection result;

(e) a soldering unit for soldering said component onto said board by heating and melting said solder; [[and]]

(f) a main controller for updating at least one of a control parameter for controlling an operation of said printer and a control parameter for controlling an operation of said component mounting unit based on at least one of said solder position detection result and said component position detection result; and

(g) a board inspection unit for inspecting said electrode and evaluating positional deviation of said electrode, said board inspection unit situated before said printer.

2. (Original) The component mounting system as defined in Claim 1 further comprising a third inspection unit for inspecting a mounting condition by recognizing said component after said soldering, and outputting a mounting inspection result.

3. (Currently Amended) A component mounting system configured by connecting a plurality of devices for manufacturing a mounted board by placing and soldering a component onto the board, said component mounting system comprising:

(a) printer for printing solder onto an electrode formed on said board;

(b) a first inspection unit for detecting a position of said printed solder and outputting a solder position detection result;

(c) a component mounting unit for picking up said component from a feeder carriage with a mounting head and placing said component onto said board;

(d) a second inspection unit for detecting a position of said component placed and outputting a component position detection result;

(e) a soldering unit for soldering said component onto said board by heating and melting said solder;

(f) a third inspection unit for inspecting a mounting condition by recognizing said component after said soldering, and outputting a mounting inspection result; and, said updating of said main controller based on feedback and/or feedforward processing of said solder position detection result and said component position detection result;

(g) abnormality evaluation means for determining the presence of any abnormal operation in at least one of said printer, said component mounting unit, and said soldering unit based on at least one of said solder position detection result, said component position detection result, and said mounting inspection result; and

(h) a board inspection unit for inspecting said electrode and evaluating positional deviation of said electrode, said board inspection unit situated before said printer.

4. (Currently Amended) A component mounting method for manufacturing a mounted board by placing and soldering a component onto a board using a component mounting system configured by connecting a plurality of devices, said method comprising:

(a) a printing step for printing solder on an electrode formed on said board using a printer;

(b) a solder position detection step for detecting a position of said printed solder and outputting a solder position detection result using a first inspection unit;

(c) a placement step for picking up said component from a component feeder carriage and placing said component onto said board using a mounting head in a component mounting unit;

(d) a component position detection step for detecting a position of said component placed and outputting a component position detection resulting using a second inspection unit;[[and]]

(e) a soldering step for soldering said component onto said board by heating and melting solder using a soldering unit; and

(f) an inspecting step before said printing step for inspecting said electrode and evaluating positional deviation of said electrode;

wherein at least one of a control parameter for controlling an operation of said printer and a control parameter for controlling an operation of said component mounting unit is updated based on at least one of said solder position detection result and said component position detection result while executing said steps.

5. (Original) The mounting method as defined in Claim 4, said method further comprising a mounting inspection step for inspecting a mounting condition by recognizing said component after said soldering, and outputting a mounting inspection result using a third inspection unit;

wherein a control parameter for controlling an operation of said soldering unit is updated based on said mounting inspection result.

6. (Currently Amended) A component mounting method for manufacturing a mounted board by placing and soldering a component onto a board using a component mounting system configured by connecting a plurality of devices, said method comprising:

(a) a printing step for printing solder on an electrode formed on said board using a printer;

(b) a solder position detection step for detecting a position of said printed solder and outputting a solder position detection result using a first inspection unit;

(c) a placement step for picking up said component from a component feeder carriage and placing said component onto said board using a mounting head in a component mounting unit;

2 (d) a component position detection step for detecting a position of said component placed and outputting a component position detection resulting using a second inspection unit;

A (e) a soldering step for soldering said component onto said board by heating and melting solder using a soldering unit;[[and]]

(f) a mounting inspection step for inspecting a mounting condition by recognizing said component after said soldering, and outputting a mounting inspection result using a third inspection unit;and

(g) an inspecting step before said printing step for inspecting said electrode and evaluating positional deviation of said electrode;

wherein the presence of any abnormal operation in at least one of said printer, said component mounting unit, and said soldering unit is determined based on at least one of said solder position detection result, said component position detection result, and said mounting inspection result while executing said steps.

7. (New) A component mounting system according to claim 1, wherein said updating of said main controller based on feedback and/or feedforward processing of said solder position detection result and said component position detection result.
